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MPSA75, MPSA77

Darlington Transistors

PNP Silicon

Features

- These are Pb-Free Devices*

MAXIMUM RATINGS

Rating	Symbol	Value	Unit	
Collector-Emitter Voltage	MPSA75 MPSA77	V _{CES}	-40 -60	Vdc
Emitter-Base Voltage		V _{EBO}	-10	Vdc
Collector Current - Continuous		I _C	-500	mAdc
Total Device Dissipation @ T _A = 25°C Derate above 25°C		P _D	625 5.0	mW mW/°C
Operating and Storage Junction Temperature Range		T _J , T _{stg}	-55 to +150	°C

THERMAL CHARACTERISTICS

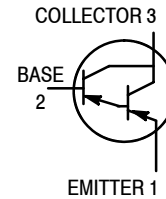
Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Ambient	R _{θJA}	200	°C/W

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

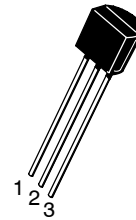


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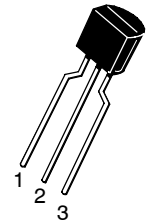
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**TO-92
CASE 29
STYLE 1**

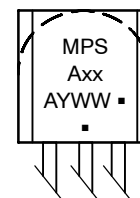


STRAIGHT LEAD
BULK PACK



BENT LEAD
TAPE & REEL
AMMO PACK

MARKING DIAGRAM



- xx = 75, or 77
- A = Assembly Location
- Y = Year
- WW = Work Week
- = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping†
MPSA75RLRPG	TO-92 (Pb-Free)	2000 / Ammo Pack
MPSA77G	TO-92 (Pb-Free)	5000 Units / Bulk

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

MPSA75, MPSA77

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic		Symbol	Min	Typ	Max	Unit
OFF CHARACTERISTICS						
Collector-Emitter Breakdown Voltage (I _C = -100 μAdc, V _{BE} = 0)	MPSA75 MPSA77	V _{(BR)CES}	-40 -60	- -	- -	Vdc
Collector-Base Breakdown Voltage (I _C = 100 μAdc, I _E = 0)	MPSA75 MPSA77	V _{(BR)CBO}	-40 -60	- -	- -	Vdc
Collector Cutoff Current (V _{CB} = -30 V, I _E = 0) (V _{CB} = -50 V, I _E = 0)	MPSA75 MPSA77	I _{CBO}	- -	- -	-100 -100	nAdc
Collector Cutoff Current (V _{CE} = -30 V, V _{BE} = 0) (V _{CE} = -50 V, V _{BE} = 0)	MPSA75 MPSA77	I _{CES}	- -	- -	-500 -500	nAdc
Emitter Cutoff Current (V _{EB} = -10 Vdc)		I _{EBO}	-	-	-100	nAdc
ON CHARACTERISTICS						
DC Current Gain (I _C = -10 mA, V _{CE} = -5.0 V) (I _C = -100 mA, V _{CE} = -5.0 V)		h _{FE}	10,000 10,000	- -	- -	-
Collector-Emitter Saturation Voltage (I _C = -100 mA, I _B = -0.1 mAdc)		V _{CE(sat)}	-	-	-1.5	Vdc
Base-Emitter On Voltage (I _C = -100 mA, V _{CE} = -5.0 Vdc)		V _{BE}	-	-	-2.0	Vdc
SMALL-SIGNAL CHARACTERISTICS						
Current-Gain - High Frequency (I _C = -10 mA, V _{CE} = -5.0 V, f = 100 MHz)		h _{fe}	1.25	2.4	-	-

MPSA75, MPSA77

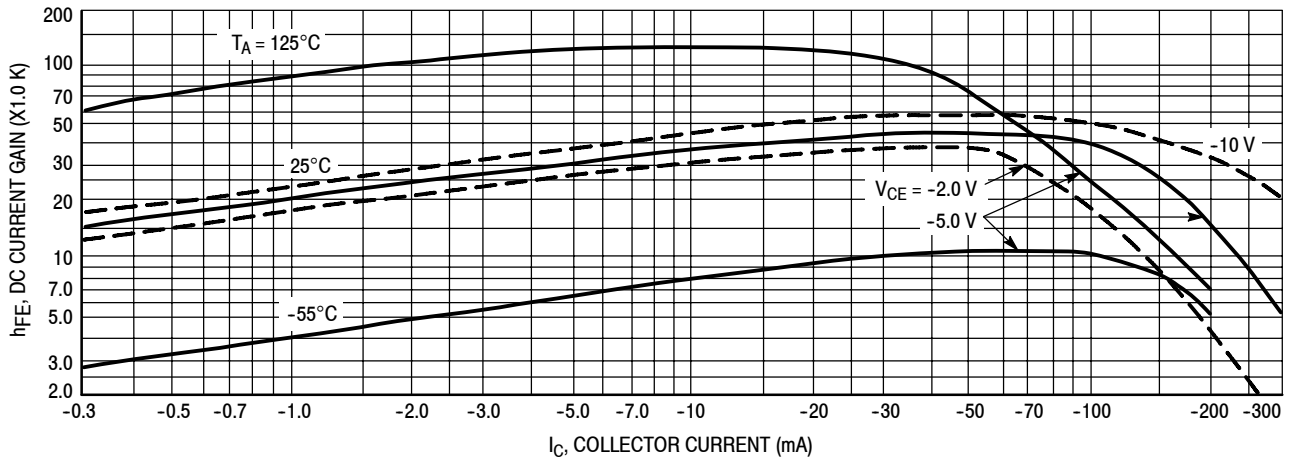


Figure 1. DC Current Gain

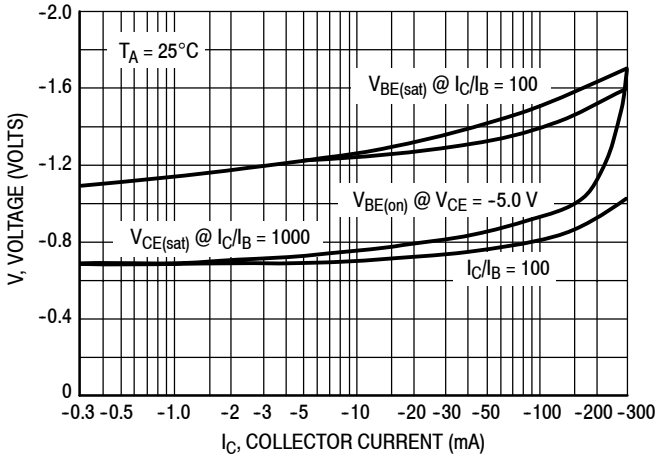


Figure 2. "On" Voltage

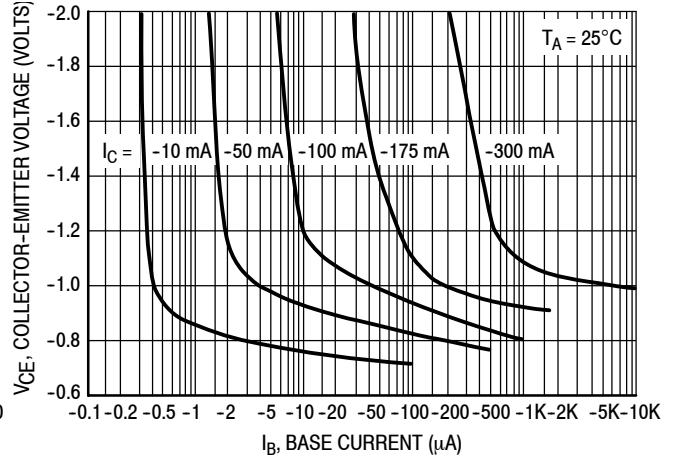


Figure 3. Collector Saturation Region

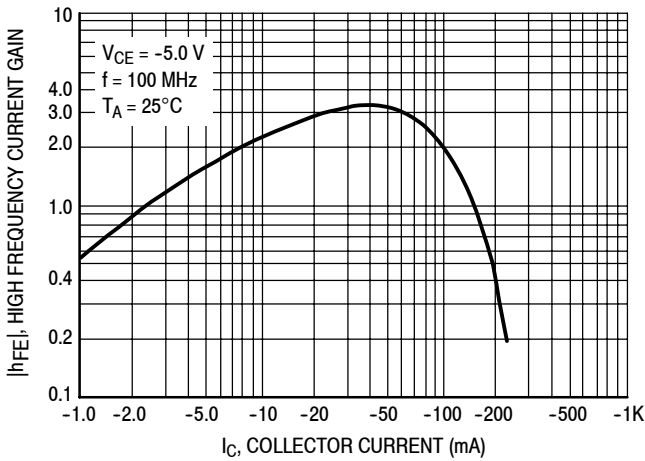


Figure 4. High Frequency Current Gain

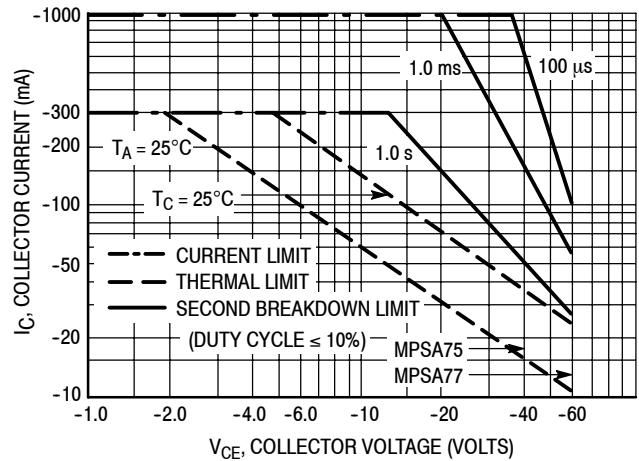
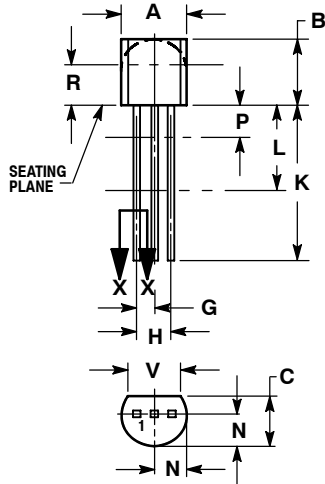


Figure 5. Active Region, Safe Operating Area

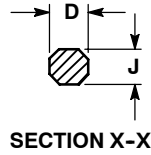
MPSA75, MPSA77

PACKAGE DIMENSIONS

TO-92 (TO-226) CASE 29-11 ISSUE AM



STRAIGHT LEAD
BULK PACK

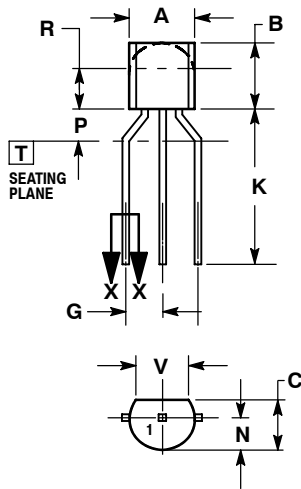


SECTION X-X

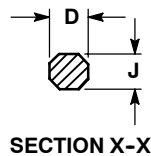
NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. CONTOUR OF PACKAGE BEYOND DIMENSION R IS UNCONTROLLED.
4. LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.175	0.205	4.45	5.20
B	0.170	0.210	4.32	5.33
C	0.125	0.165	3.18	4.19
D	0.016	0.021	0.407	0.533
G	0.045	0.055	1.15	1.39
H	0.095	0.105	2.42	2.66
J	0.015	0.020	0.39	0.50
K	0.500	---	12.70	---
L	0.250	---	6.35	---
N	0.080	0.105	2.04	2.66
P	---	0.100	---	2.54
R	0.115	---	2.93	---
V	0.135	---	3.43	---



BENT LEAD
TAPE & REEL
AMMO PACK



SECTION X-X


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. CONTOUR OF PACKAGE BEYOND DIMENSION R IS UNCONTROLLED.
4. LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

DIM	MILLIMETERS	
	MIN	MAX
A	4.45	5.20
B	4.32	5.33
C	3.18	4.19
D	0.40	0.54
G	2.40	2.80
J	0.39	0.50
K	12.70	---
N	2.04	2.66
P	1.50	4.00
R	2.93	---
V	3.43	---

STYLE 1:

1. EMITTER
2. BASE
3. COLLECTOR

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